

Flex on Glass for mmWave Applications

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Outline

- □ Research Objectives
- Prior Work
- □ Application Automotive Radar
- Individual Component Analysis
- □ Future Work
- Projected Timeline





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Research Objectives



- Design, fabricate, and integrate passives (transmission line, antennas, couplers, etc.) and active components (ICs) onto flexible glass substrates (Schott AF32)
 - Stack-ups will include metallization (screen printing, inkjet printing, and aerosol jet printing) on bare glass as well as layers of build up materials to use subtractive etching and semi-additive processing
- □ Focus primarily on mmWave applications

□ Automotive

Prior Work

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- Direct metallization (screen printing) onto Kapton polyimide (Pyralux AP and Kapton HF) and PET
 - Transmission Lines (Microstrip and CPW), Power Inductors, and Patch Antennas
- Components underwent both tensile (a) and compressive (b) bending using adaptive curvature bending





Ref: S. Sivapurapu, C. Mehta, R. Chen, Y. Zhou, X. Jia, M. Bellaredj, P. Kohl, S. Sitaraman, M. Swaminathan, "Multi-physics Modeling Characterization of Aerosol Jet Printed Transmission Lines"





Georgia Tech



Ref: S. Sivapurapu, C. Mehta, R. Chen, Y. Zhou, X. Jia, M. Bellaredj, P. Kohl, S. Sitaraman, M. Swaminathan, "Multi-physics Modeling and Characterization of Components on Flexible Substrates"

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Prior Work (cont.)

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- Mismatch between measurement and simulation occurs to tool limitation to account of positional strain inside of EM simulation
 - Occurs at small panel separation (maximum bending)



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- Begin with Taiyo Stretchable Ag Conductive Paste both directly on glass using Screen Printing
- □ Low temperature processing (90°C)
- Major advantage compared to other Ag Conductive Pastes is minimizing change in resistance while stretching compared to other products
 Stretch testing completed up to 20% elongation without fracture

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- Expected Conversion Gain: -5 dB at 150 MHz (cutoff frequency for baseband processing)
- \square R is 200 Ω and C is 5 pF
- Diodes will be off-the-shelf Schottky Diodes
- □ RF Input expected to be -30 dBm

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Patch Antenna – Adaptive Curvature Bending – Radiation Pattern



Flat Peak Gain: 11.2 dBi



Changing the panel separation significantly changes the radiation pattern



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Patch Antenna – Adaptive Curvature Bending Radiation Pattern

Flat Peak Gain: 11.1 dB



At small enough panel separations, the Yagi Antenna changes from End-fire to Broadside

Future Work



- Begin fabrication on 30 um Schott AF32 glass with both direct metallization of glass (printing) as well as with build up layers
- Measure individual components (antenna, transmission line, coupler, etc.)
- □ Integrate components for full system analysis before chip attach
- □ Chip attach and integrate system (Chip last module)

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Timeline for Proposed Work

| | 2019 | 2019 2020 | | | | | 2021 | | |
|-----------------------------|------|-----------|----|----|----|----|------|----|--|
| | Q4 | Q1 | Q2 | Q3 | Q4 | Q1 | Q2 | Q3 | |
| Individual Component | | | | | | | | | |
| Design | | | | | | | | | |
| Individual Component | | | | | | | | | |
| Fabrication | | | | | | | | | |
| Individual Component | | | | | | | | | |
| Characterization (including | | | | | | | | | |
| bending) | | | | | | | | | |
| Component and System | | | | | | | | | |
| Level Design | | | | | | | | | |
| System Level Fabrication | | | | | | | | | |
| Full System Level | | | | | | | | | |
| Characterization | | | | | | | | | |

Light Blue: Component Level Design Dark Blue: System Level Integration (Chip Last)

